

/ Descriptions

TO-220F

Schottky Barrier Diode in a TO-220F Plastic Package.

/ Features

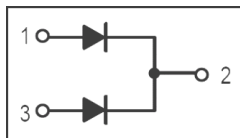
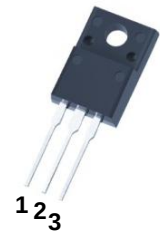
Low forward voltage drop, low power losses, High efficiency operation.

/ Applications

OR-ing

DC-DC

For use in high frequency inverters, switching power supplies, freewheeling diodes, OR-ing diode, dc-to-dc converters and reverse battery protection.

/ Equivalent Circuit**/ Pinning**

PIN1 Anode PIN 2 Cathode PIN 3 Anode

/ h_{FE} Classifications & Marking

See Marking Instructions.

/ Absolute Maximum Ratings(Ta=25)

Parameter	Symbol	Rating	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RM} V_{RSM} V_{DC}	200	V
RMS Voltage	V_{RMS}	140	V
Average Rectified Forward Current	$I_{F(AV)}$	2×5	A
Non Repetitive Peak Surge Current	I_{FSM}	80	A
Thermal Resistance Junction to Case	R_{JC}	4.5	/W
Junction and Storage Temperature Range	T_j T_{stg}	-40 +150	

/ Electrical Characteristics(Ta=25)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Breakdown Voltage	V_{BR}	$I_R=1mA(Ta=25)$	200			V
Forward Voltage	V_F	$I_F=2.5A(Ta=25)$		0.81	0.95	V
		$I_F=2.5A(Ta=125)$		0.62	0.75	V
		$I_F=5A(Ta=25)$		1.10	1.60	V
		$I_F=5A(Ta=125)$		0.70	0.75	V
Instantaneous Reverse Current	I_R Note 1	$V_R=200V(Ta=25)$			50	A
		$V_R=200V(Ta=125)$		1.5	10	mA

/Notes

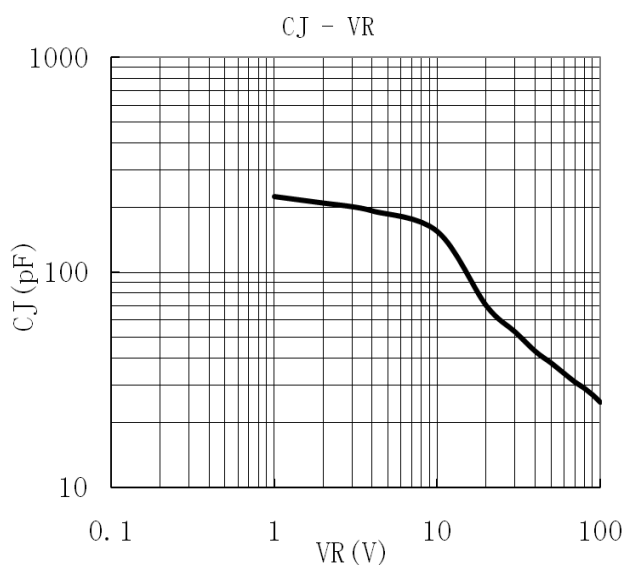
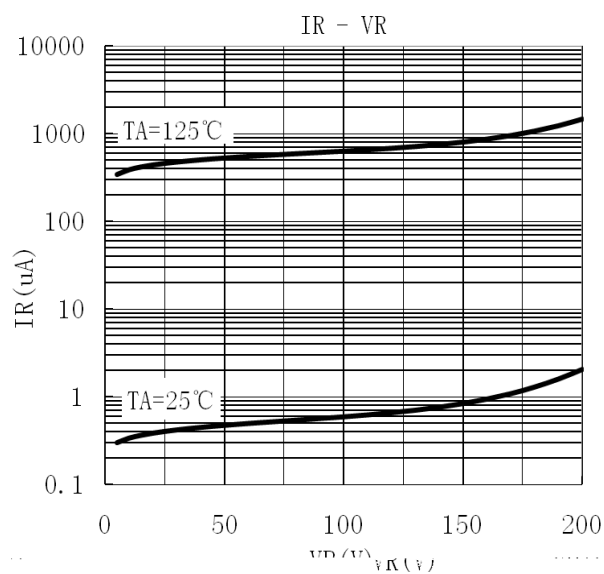
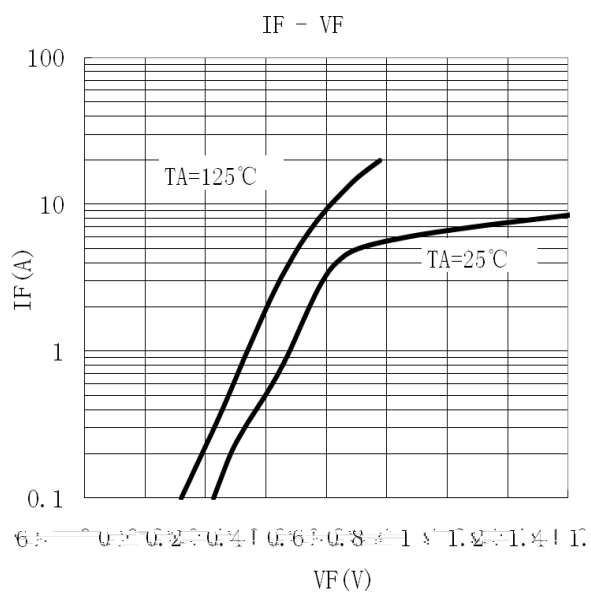
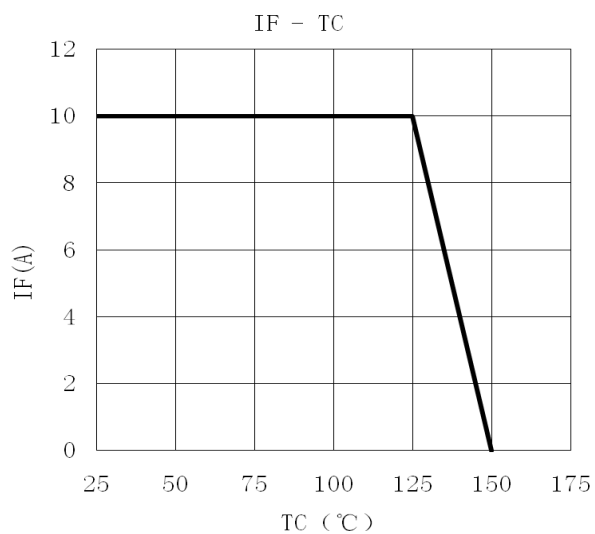
1.

Short duration pulse test used to minimize self-heating effect.

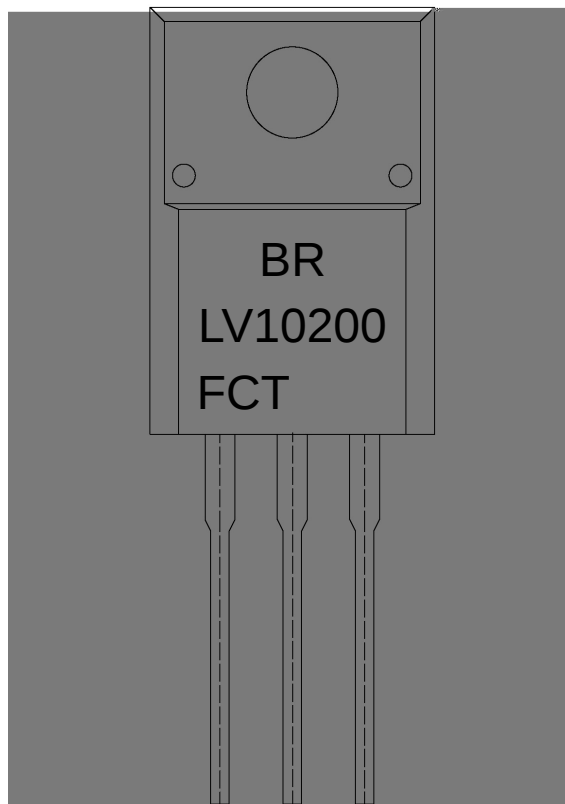
2.

Unless otherwise noted, values for the parameters of a single chip

/ Electrical Characteristic Curve



/ Marking Instructions



BR

LV10200

F:

CT:

Note:

BR: Company Code

LV10200: Product Type Code.

F Package Code

CT: Internal Structure

****: Lot No. Code, code change with Lot No.

() / Temperature Profile for Dip Soldering(Pb-Free)



Note:

- | | | | | | |
|---|-------|-----|-----------|---|--------------------------------------|
| 1 | 25 | 150 | 60 | 90sec; | 1.Preheating:25~150 , Time:60~90sec. |
| 2 | 255±5 | | 5±0.5sec; | 2.Peak Temp.:255±5 , Duration:5±0.5sec. | |
| 3 | | 2 | 10 | /sec. | 3. Cooling Speed: 2~10 /sec. |

/ Resistance to Soldering Heat Test Conditions

270±5 10±1 sec. Temp.:270±5 Time:10±1 sec

/ Packaging SPEC.

/ BULK

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	只 袋	袋 盒	只 盒	盒 箱	只 箱	袋	盒	箱

/ TUBE

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	只 套管	套管 盒	只 盒	盒 箱	只 箱	套管	盒	箱

/ Notices